SCBS190A - JANUARY 1991 - REVISED JULY 1994

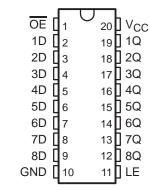
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- ESD Protection Exceeds 2000 V Per MIL-STD-883C, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0)
- Latch-Up Performance Exceeds 500 mA Per JEDEC Standard JESD-17
- Typical V<sub>OLP</sub> (Output Ground Bounce)
  1 V at V<sub>CC</sub> = 5 V, T<sub>A</sub> = 25°C
- High-Drive Outputs (-32-mA I<sub>OH</sub>, 64-mA I<sub>OL</sub>)
- Package Options Include Plastic Small-Outline (DW) and Shrink Small-Outline (DB) Packages, Ceramic Chip Carriers (FK), and Plastic (N) and Ceramic (J) DIPs

### description

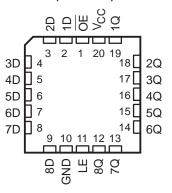
These 8-bit latches feature 3-state outputs designed specifically for driving highly capacitive or relatively low-impedance loads. They are particularly suitable for implementing buffer registers, I/O ports, bidirectional bus drivers, and working registers.

The eight latches of the 'ABT573 are transparent D-type latches. While the latch-enable (LE) input is high, the Q outputs follow the data (D) inputs. When the latch enable is taken low, the Q outputs are latched at the logic levels set up at the D inputs.

SN54ABT573 . . . J PACKAGE SN74ABT573 . . . DB, DW, OR N PACKAGE (TOP VIEW)



SN54ABT573...FK PACKAGE (TOP VIEW)



A buffered output-enable ( $\overline{OE}$ ) input can be used to place the eight outputs in either a normal logic state (high or low logic levels) or a high-impedance state. In the high-impedance state, the outputs neither load nor drive the bus lines significantly. The high-impedance state and increased drive provide the capability to drive bus lines without need for interface or pullup components.

OE does not affect the internal operations of the latches. Old data can be retained or new data can be entered while the outputs are in the high-impedance state.

To ensure the high-impedance state during power up or power down,  $\overline{OE}$  should be tied to  $V_{CC}$  through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

The SN74ABT573 is available in TI's shrink small-outline package (DB), which provides the same I/O pin count and functionality of standard small-outline packages in less than half the printed-circuit-board area.

The SN54ABT573 is characterized for operation over the full military temperature range of  $-55^{\circ}$ C to  $125^{\circ}$ C. The SN74ABT573 is characterized for operation from  $-40^{\circ}$ C to  $85^{\circ}$ C.

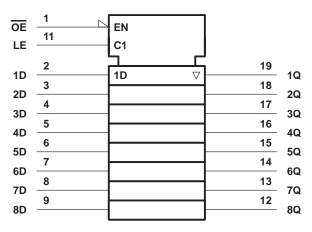
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SCBS190A - JANUARY 1991 - REVISED JULY 1994

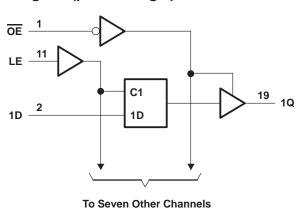
#### **FUNCTION TABLE** (each latch)

	INPUTS	OUTPUT	
OE	LE	D	Q
L	Н	Н	Н
L	Н	L	L
L	L	Χ	Q <sub>0</sub>
Н	X	Χ	Z

### logic symbol†



### logic diagram (positive logic)



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V <sub>CC</sub>	0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)	
Voltage range applied to any output in the high state or power-off	state, V <sub>O</sub> 0.5 V to 5.5 V
Current into any output in the low state, IO: SN54ABT573	96 mA
SN74ABT573	128 mA
Input clamp current, $I_{IK}$ ( $V_I < 0$ )	–18 mA
Output clamp current, I <sub>OK</sub> (V <sub>O</sub> < 0)	–50 mA
Maximum power dissipation at $T_A = 55^{\circ}C$ (in still air) (see Note 2)	: DB package 0.6 W
	DW package 1.6 W
	N package 1.3 W
Storage temperature range	65°C to 150°C

<sup>‡</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.



<sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

<sup>2.</sup> The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils, except for the N package, which has a trace length of zero. For more information, refer to the Package Thermal Considerations application note in the 1994 ABT Advanced BiCMOS Technology Data Book, literature number SCBD002B.

SCBS190A - JANUARY 1991 - REVISED JULY 1994

### recommended operating conditions (see Note 3)

					SN74A	UNIT	
			MIN	MAX	MIN	MAX	UNIT
Vcc	Supply voltage		4.5	5.5	4.5	5.5	V
VIH	High-level input voltage				2		V
V <sub>IL</sub>	V <sub>IL</sub> Low-level input voltage					0.8	V
V <sub>I</sub> Input voltage				VCC	0	VCC	V
IOH	High-level output current					-32	mA
lOL	OL Low-level output current			48		64	mA
Δt/Δν	Input transition rise or fall rate	Outputs enabled		5		5	ns/V
TA	Operating free-air temperature		-55	125	-40	85	°C

NOTE 3: Unused or floating inputs must be held high or low.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

DADAMETER	TEST CONDITIONS			Т	T <sub>A</sub> = 25°C			BT573	SN74ABT573		
PARAMETER				MIN	TYP <sup>†</sup>	MAX	MIN	MAX	MIN	MAX	UNIT
VIK	$V_{CC} = 4.5 \text{ V},$	I <sub>I</sub> = -18 mA				-1.2		-1.2		-1.2	V
	$V_{CC} = 4.5 \text{ V},$	$I_{OH} = -3 \text{ mA}$		2.5			2.5		2.5		
\/-··	$V_{CC} = 5 \text{ V}$ , $IOH = -3 \text{ mA}$			3			3		3		$  $ $_{\vee}$ $ $
VOH	V <sub>CC</sub> = 4.5 V	$I_{OH} = -24 \text{ mA}$		2			2				V
	VCC = 4.5 V	$I_{OH} = -32 \text{ mA}$		2*					2		
Voi	V00 - 45 V	I <sub>OL</sub> = 48 mA				0.55		0.55			V
VOL	V <sub>CC</sub> = 4.5 V	I <sub>OL</sub> = 64 mA				0.55*				0.55	V
lį	$V_{CC} = 5.5 \text{ V},$	V <sub>I</sub> = V <sub>CC</sub> or GNI	)			±1		±1		±1	μΑ
I <sub>OZH</sub>	$V_{CC} = 5.5 V$ ,	V <sub>O</sub> = 2.7 V				50		10		50	μΑ
I <sub>OZL</sub>	$V_{CC} = 5.5 V$ ,	V <sub>O</sub> = 0.5 V				-50		-10		-50	μΑ
l <sub>off</sub>	$V_{CC} = 0$ ,	$V_I$ or $V_O \le 4.5 \text{ V}$				±100				±100	μΑ
ICEX	$V_{CC} = 5.5 V$ ,	V <sub>O</sub> = 5.5 V	Outputs high			50		50		50	μΑ
IO <sup>‡</sup>	$V_{CC} = 5.5 V$ ,	V <sub>O</sub> = 2.5 V		-50	-100	-180	-50	-180	-50	-180	mA
			Outputs high		1	250		250		250	μΑ
ICC	I AI = ACC OL GIAD		Outputs low		24	30		30		30	mA
		Outputs disabled		0.5	250		250		250	μΑ	
Δl <sub>CC</sub> §	V <sub>CC</sub> = 5.5 V, Other inputs at	One input at 3.4	V,			1.5		1.5		1.5	mA
C <sub>i</sub>	V <sub>I</sub> = 2.5 V or 0.5 V			3						pF	
Co	$V_0 = 2.5 \text{ V or } 0$	0.5 V			6						pF

<sup>\*</sup> On products compliant to MIL-STD-883, Class B, this parameter does not apply.

<sup>†</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ .

<sup>‡</sup> Not more than one output should be tested at a time, and the duration of the test should not exceed one second.

<sup>§</sup> This is the increase in supply current for each input that is at the specified TTL voltage level rather than V<sub>CC</sub> or GND.

## SN54ABT573, SN74ABT573 OCTAL TRANSPARENT D-TYPE LATCHES WITH 3-STATE OUTPUTS

SCBS190A - JANUARY 1991 - REVISED JULY 1994

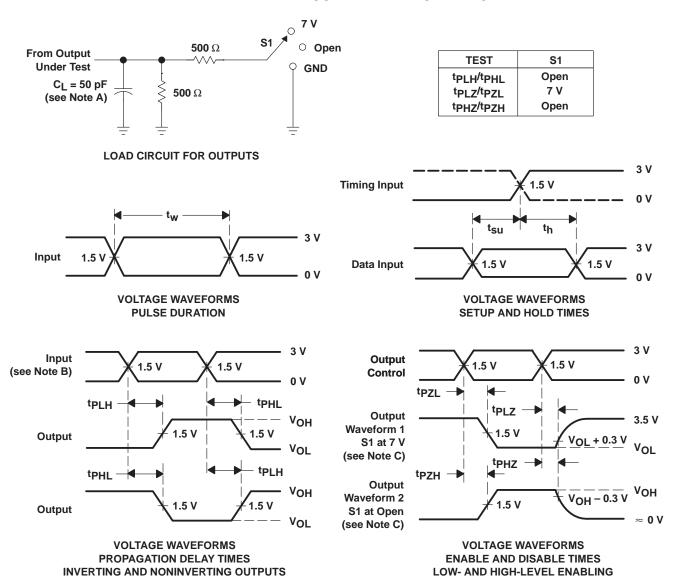
# timing requirements over recommended ranges of supply voltage and operating free-air temperature (unless otherwise noted) (see Figure 1)

		V <sub>CC</sub> =	= 5 V, 25°C	SN54ABT573		SN74ABT573		UNIT	
			MIN	MAX	MIN	MAX	MIN	MAX	
t <sub>W</sub>	t <sub>W</sub> Pulse duration, LE high		3.3		3.3		3.3		ns
	Catura time, data hatara I E	High	1.9		2.5		1.9		
เรน	$t_{SU}$ Setup time, data before LE $\downarrow$	Low	1.5		2.5		1.5		ns
t <sub>h</sub>	$t_h$ Hold time, data after LE $\downarrow$		1		2.5		1		ns

# switching characteristics over recommended ranges of supply voltage and operating free-air temperature, $C_L$ = 50 pF (unless otherwise noted) (see Figure 1)

PARAMETER	FROM	TO (OUTPUT)		V <sub>CC</sub> = 5 V, T <sub>A</sub> = 25°C			SN54ABT573		SN74ABT573	
	(INPUT)	(OUTPUT)	MIN	TYP	MAX	MIN	MAX	MIN	MAX	
t <sub>PLH</sub>	D	Q	1.9	3.2	5.4	1.4	6.4	1.9	5.9	
<sup>t</sup> PHL		γ	2.2	4.2	5.7	1.6	6.7	2.2	6.2	ns
t <sub>PLH</sub>	LE	Q	2.2	4	6.1	2	7.1	2.2	6.6	
<sup>t</sup> PHL		y	3.2	5.2	6.7	2.8	7.5	3.2	7.2	ns
<sup>t</sup> PZH	ŌĒ	Q	1.2	3.2	4.7	0.8	6.2	1.2	5.2	
t <sub>PZL</sub>	OE	g	2.7	4.7	6.2	2	7.2	2.7	6.7	ns
t <sub>PHZ</sub>	ŌĒ	Q	2.5	4.9	6.4	2.2	7.7	2.5	6.9	ne
tPLZ		γ	2	4.2	6	1.4	7	2	6.5	ns

#### PARAMETER MEASUREMENT INFORMATION



NOTES: A. C<sub>L</sub> includes probe and jig capacitance.

- B. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_f \leq$  2.5 ns,  $t_f \leq$  2.5 ns.
- C. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- D. The outputs are measured one at a time with one transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

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